

### **Description**

The VSM3402A uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

•  $V_{DS} = 30V, I_{D} = 3A$ 

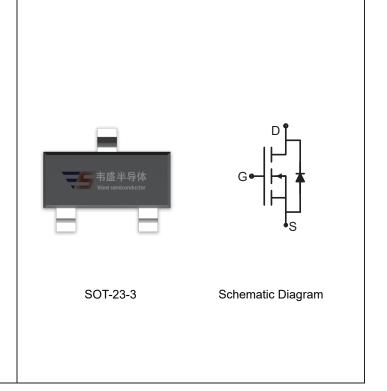
 $R_{DS(ON)}$  <  $85 m\Omega$  @  $V_{GS}$  =2.5V

 $R_{DS(ON)}$  < 70m $\Omega$  @  $V_{GS}$ =4.5V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

# **Application**

- Battery protection
- Load switch
- Power management



# Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM3402A-S2	VSM3402A	SOT-23-3	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T<sub>A</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	30	V
Gate-Source Voltage	V <sub>G</sub> s	±12	V
Drain Current-Continuous	I <sub>D</sub>	3	Α
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	20	А
Maximum Power Dissipation	P <sub>D</sub>	0.9	W
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	°C

## **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	138	°C/W

#### **Electrical Characteristics (T<sub>A</sub>=25**°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	30	-	-	V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =20V,V <sub>GS</sub> =0V	-	-	1	μA	



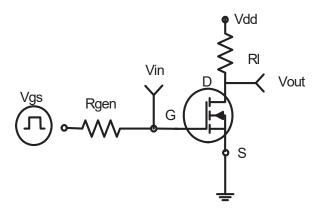
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)	·					
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	0.6	0.85	1.4	V
	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3A	-	50	60	mΩ
Drain-Source On-State Resistance		$V_{GS}$ =4.5V, $I_D$ =3 A	-	55	70	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =2A	-	68	85	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =3A	14	-	-	S
Dynamic Characteristics (Note4)	·					
Input Capacitance	C <sub>lss</sub>	\/ -10\/\/ -0\/	-	235	-	PF
Output Capacitance	Coss	- V <sub>DS</sub> =10V,V <sub>GS</sub> =0V, F=1.0MHz	-	35	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F-1.UIVIFIZ	-	18	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	3.5	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =15 $V$ , $I_{D}$ =1 $A$	-	1.5	-	nS
Turn-Off Delay Time	$t_{d(off)}$	$V_{GS}$ =4.5 $V$ , $R_{GEN}$ =6 $\Omega$	-	17.5	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	2.5	-	nS
Total Gate Charge	Qg	V <sub>DS</sub> =15V,I <sub>D</sub> =3A,V <sub>GS</sub> =4.5V	-	4.7	-	nC
Gate-Source Charge	$Q_{gs}$		-	0.95	-	nC
Gate-Drain Charge	$Q_{gd}$		-	1.6	-	nC
Drain-Source Diode Characteristics	•					
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =3A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	3	Α

#### Notes:

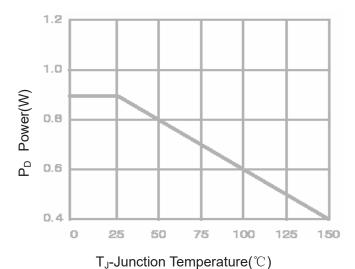
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



## **Typical Electrical and Thermal Characteristics**



**Figure 1:Switching Test Circuit** 



**Figure 3 Power Dissipation** 

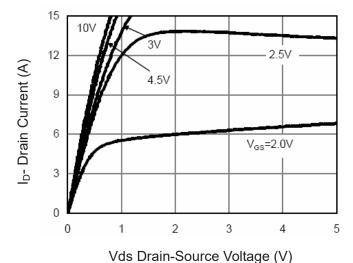
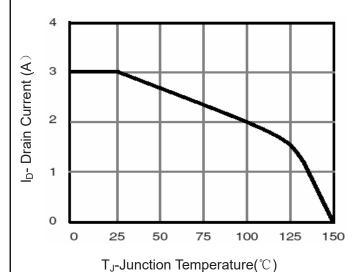


Figure 5 Output Characteristics



Figure 2:Switching Waveforms



**Figure 4 Drain Current** 

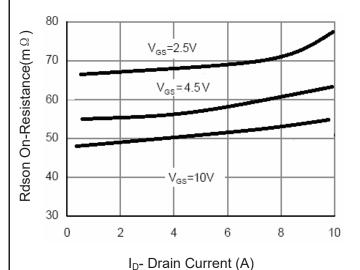
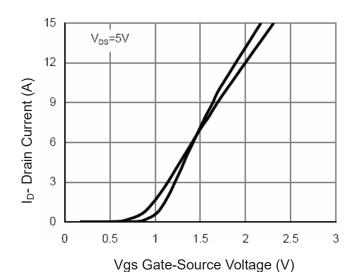


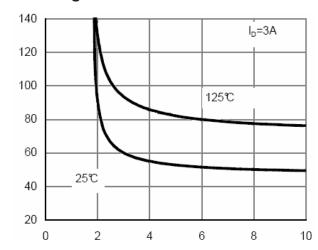
Figure 6 Drain-Source On-Resistance



Rdson On-Resistance(m 2)



**Figure 7 Transfer Characteristics** 



Vgs Gate-Source Voltage (V)

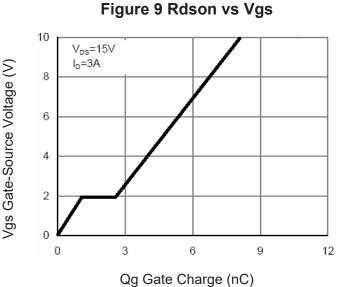


Figure 11 Gate Charge

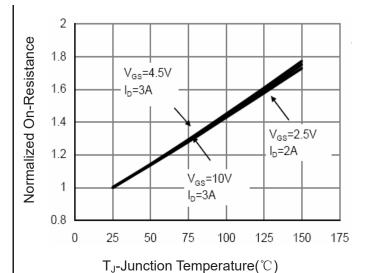


Figure 8 Drain-Source On-Resistance

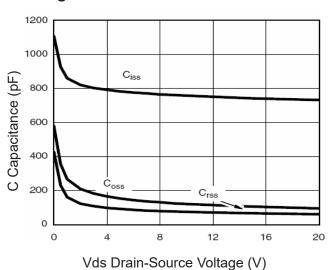


Figure 10 Capacitance vs Vds

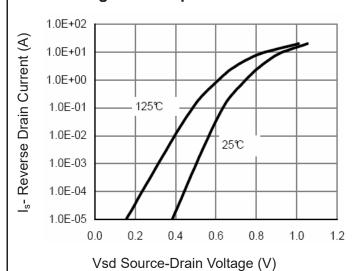


Figure 12 Source- Drain Diode Forward



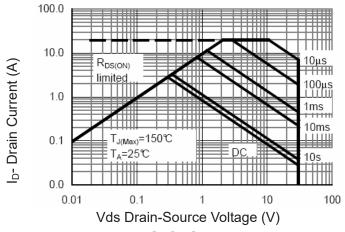
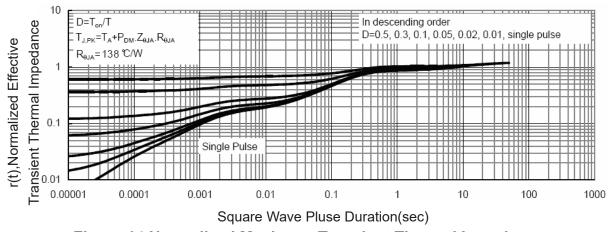


Figure 13 Safe Operation Area



**Figure 14 Normalized Maximum Transient Thermal Impedance**